# Spherical Boron Nitride

## Specification

GBN-S120

#### Product Features

High filling rate, high thermal conductivity, high particle strength, high tap dens low dielectric constant, lower specific surface area compared with plate boron nitride.

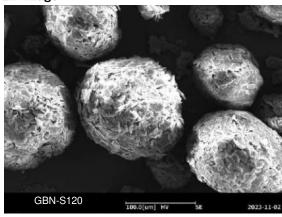
## **Application**

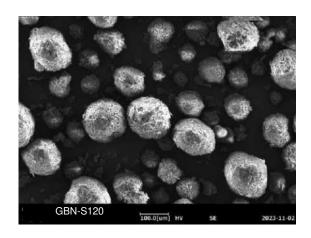
For thermal interface material with lower dielectric constant or higher dielectric resistance, such as thermal pad, thermal conductive prepreg, thermal conductive plastic.

## Typical Properties

	thermal pad,	thermal pad, thermal conductive prepreg, thermal conductive plastic.				
	Typical Prop	erties				
	ltem		Unit	Typical Value	Method/Device	
	Particle Size	(D50)	μm	123. 497	Light Scattering/OMEC Top Sizer	
	S.S.A.  Electrical  Conductivity		m²/g	1. 98	BSD-BET-400/ Specific Surface Area Analyzer	
			μS/cm	64. 28	Mettler FE-38/ Conductivity Meter	
	рН		-	9. 04	Mettler FE-28 /pH Meter	
	Tap Density		g/cm3	0. 58	BT-313/ tap density tester	

#### SEM Image





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### Typical Packaging

10Kg/Bag

Paper outer bag + PE inner bag + cardboard boxes

## Period of Validity

It is recommended to use this product within 12 months. If it is overdue, the product quality status shall be reevaluated.

#### Handling and Storage

When using, wear a dust mask to prevent dust inhalation. Keep the container sealed and stored in a cool, dry and well ventilated area.